



PATENT APPLICATION  
Serial No. 10/043,709

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**CERTIFICATE OF MAILING (37 C.F.R. § 1.8)**

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Box Non-Fee Amendment, Washington, D.C. 20231, on this 4 day of December, 2002.

Signed:

Printed name:

Kathy Dixon

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re : Kuo-Yu Chou, et al. : Docket No. 67,200-603  
Serial No. : 10/043,709 : Art Unit No. 2814  
Filing Date : January 9, 2002 : Examiner: Le, Thao X

01/02/2003 TDAWKINS 00000005 10043709

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72.00 OP

**A SINGLE LAYER WIRING BOND PAD WITH OPTIMUM  
AL FILM THICKNESS IN CU/FSG PROCESS FOR DEVICES  
UNDER PADS**

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

November 25, 2002

Sir:

In response to the Official Action dated September 4, 2002, Applicants respectfully request reconsideration and further examination of all claims presented and entry of the following Amendment into the above-captioned patent application. Each of the amendments finds full support in the claims, specification, or drawings as filed. Therefore, please amend the above-captioned patent application, without prejudice, as follows: